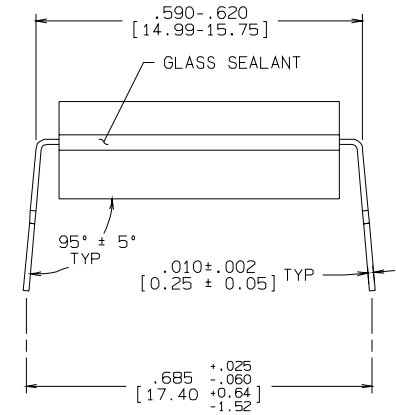
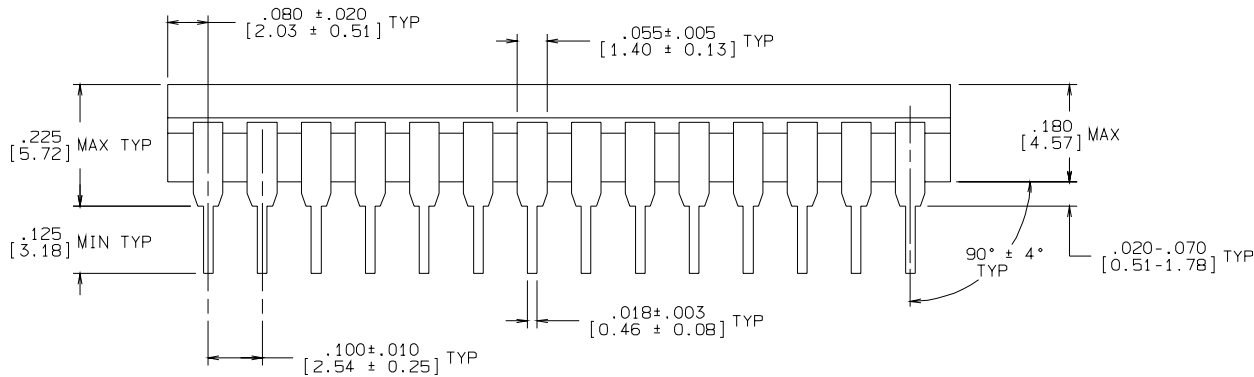
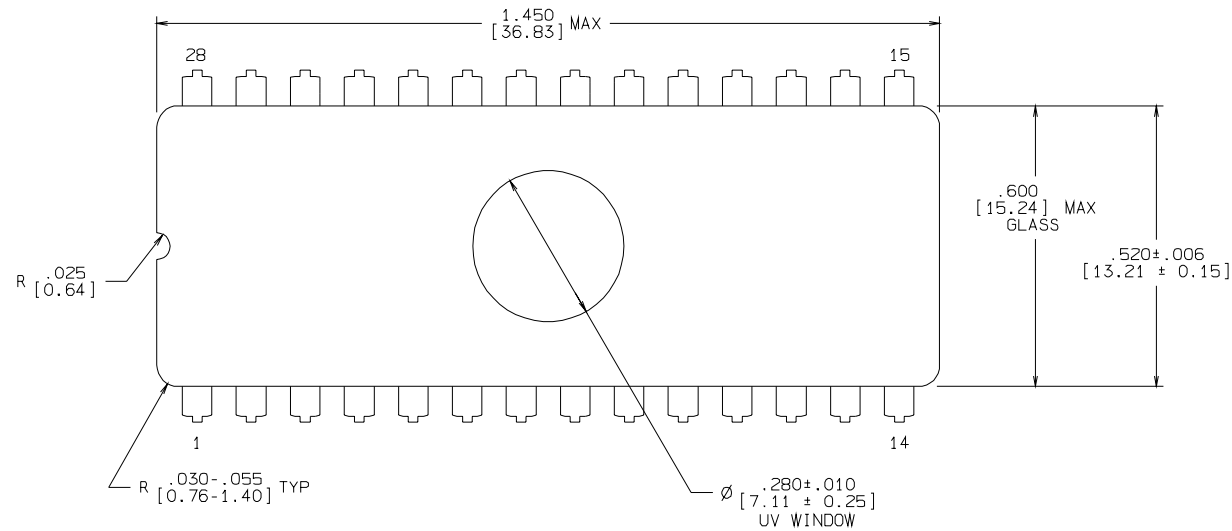


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE PER CURRENT STD; REDRAW	10000	09/15/93	TL/



CONTROLLING DIMENSION: MILLIMETER

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE 200 MICROINCHES / 5.08 MICROMETERS  
MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- BUMPERS ARE AVAILABLE ON CERTAIN PRODUCTS.  
BUMPERS WILL ADD .040IN / 1.02mm MAX TO THE LENGTH OF PACKAGE.
- JEDEC REGISTRATION M0-103, VARIATION AB, DATED 02/1990.

MIL-M-38510  
CONFIGURATION CONTROL

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN T. LEQUANG	09/15/93	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFGTG. CHK.		CERDIP (JQ), 28 LEAD, EPROM, SMALL WINDOW	
ENGR. CHK.			
APPROVAL			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	N/A	C	MKT-J28A-Q
	DO NOT SCALE DRAWING	SHEET	1 OF 1